Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]
HP ProDesk 400 G6 SFF Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>5</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain ______</td>
<td></td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at [EL-MF877-01](EL-MF877-01)
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>(gel/paste) and toner</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Star screwdriver</td>
<td>OD 3.3mm</td>
</tr>
<tr>
<td>Cross screwdriver</td>
<td>OD 3.0mm</td>
</tr>
<tr>
<td>Cross screwdriver</td>
<td>OD 6.0mm</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove side panel
2. Remove front bezel
3. Unplug ODD & HDD cables
4. Remove drive cage
5. Remove FIO cage
6. Remove ODD & HDD
7. Remove all cables
8. Remove fan duct
9. Remove cooler
10. Remove CPU
11. Remove Memory
12. Remove WLAN module
13. Remove all PCIEXP cards
14. Remove card reader
15. Remove antenna cable
16. Remove MB and battery
17. Remove PSU
18. Remove speaker

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Template Revision C

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3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Release thumb screw on the chassis rear side.
   Push side panel in the end as shown, and then pick up from chassis.
   See photo 1, 2
   Screw tool: Cross screwdriver OD 6.0mm.
2. Release 4 bezel latches from chassis by pulling outwards the bezel latches then as shown.

See Photo 3

Pick up bezel in the order as shown.

See Photo 4

1. Rotate bezel until the bezel latches align this line.

2. Lift up bezel away from chassis.
3 Unplug ODD & HDD cables as shown.

See Photo 5

Photo 5

Unplug ODD & HDD cables as shown.
4 Press HDD cage first then push button as shown.

See Photo 6

Rotation drive cage then pass through HDD cables to drive cage then remove drive cage as shown.

See Photo 7, 8

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Press HDD cage first then push button as shown.

See Photo 6

Rotation drive cage then pass through HDD cables to drive cage then remove drive cage as shown.

See Photo 7, 8
5  Pick up FIO bracket from chassis as shown.  
   See Photo 9

6  Release 4 screws then pull up HDD from drive cage as shown.  
   See Photo 10, 11  
   Screw tool:  
   Star screwdriver OD 3.3mm.

Photo 9

Photo 10
Push ODD latch then pull ODD as shown.
See Photo 12, 13
7 Release all cables

See Photo 14, 15, 16, 17, 18
8 Push fan duct latch then pick up fan duct from chassis as shown.
See Photo 19, 20

Photo 19

Photo 20
9. Release 4 screws from cooler then unplug cable as shown.

**See Photo 21, 22**

**Screw tool:**
Star screwdriver OD 3.3mm.

![Photo 21](image1)

![Photo 22](image2)
Unlock CPU socket latch and open cover then pick up CPU as shown. See Photo 23, 24
11 Press memory slot levers by pulling outward.
Then pull up memory as shown.
See Photo 25

12 Release WLAN card screw then pull up WLAN card from MB as shown.
See Photo 26, 27
Screw tool: Cross screwdriver OD 3.0mm.
Open slot lock cover then pull up all PCIEXP cards as shown.

See Photo 28, 29

Release one screw then pull up card reader as shown.

See Photo 30, 31

Screw tool: Star screwdriver OD 3.3mm.
Release front antenna screw then pull up antenna cable.
Press rear antenna cover latch then pull up cover from chassis.
Release rear antenna screw then pull up antenna cable.
See Photo 32, 33, 34, 35, 36
Screw tool: Cross screwdriver OD 3.0mm.
16 Release betty and 8 screws then pick up MB to release from chassis in the order as shown.

See Photo 37, 38

Screw tool:
Star screwdriver OD 3.3mm.
17 Release 4 screws as shown.
Push PSU latch then pull PSU then pick up PSU from chassis as shown.
See Photo 39, 40, 41
Screw tool: Star screwdriver OD 3.3mm.

18 Release one screw then pick up speaker from chassis as shown.
See Photos 42, 43
Screw tool: Star screwdriver OD 3.3mm.

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